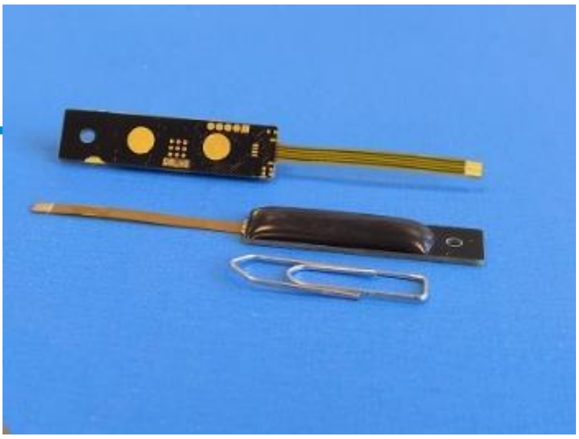
PRODUCT DATASHEET

iID® Read Write Interfaces



iID® Q8 module

HF-RFID read/write module

iID®Q8 module is a ultracompact size, multi standard HF (13.56MHz) RFID module with integrated RF electronic, on board antenna and full standard support. Integration of Q8 provides best opportunities for product traceability supporting item identification and originality check as well as TELID® sensor applications.

iID®Q8 module supports multiple RF transponder chips based on ISO communication standards ISO15693 and ISO1443A/B as well as NFC support as well as support for proprietary chip types.

microsensys offers an attractive component platform for RFID solutions –transponders, smart readers and modules combined with practical software tools.

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This data sheet is subject to change.
contact microsensys for latest information

Q8board-002

General:	HF RFID read/write communication module	ultracompact, short range
Contactless interface:	iID®2000 / iID®3000	closed coupling RFID system
RFID frequency:	13.56 MHz	
RFID Standards:		ISO15693, ISO 14443A/B, NFC
Chip Solutions:		I-CODE®, Tag-it®, my-D®, Mifare®, iID®M, iID®G, mic3® chip, TELID® sensors, inside contactless pico-TAG
Operating Distance:	0 ... 15 mm	depending on transponder and environmental conditions
Reader Antenna:		integrated printed antenna P0808
*Field Direction***:**		top and bottom, orthogonal (integrated antenna)
HOST interface:	RS232TTL	Baud Rate: 57.6 kbps
Power Supply:	3.3V	stabilized, low noise (5V version on request)
Current consumption:		typ. 20mA (IDLE), typ. 120mA (RF active)
Connector:		flex cable (4 wire) or solder pad, optional FH34SRJ-4S-0.5SH
Protocol interface:		iID® 3000 PRO wire interface specification
Software interface :		iID® driver engine (Windows, Android)
RF Security features:	supported	
Lock:		supported
Read/Write Password:		supported
Authentication:		128bit AES, on request*
Housing:	board module	glass fibre substrate, partial epoxy package
Device size:		32 x 8 x 2 mm³
Mounting instruction:		glue, screw (M1.6) or snap mechanism, no direct metal environment
Protection Class:		depending on customers integration
Environmental parameters:	depending on customers integration	
Operating Temperature:		-20°C ... +60°C
Storage Temperature:		-25°C ... +70°C
Emissions:	examine for EN 300330*	
Remark:		base module for customized OEM solution

Type :	**23.38.720.00**	**23.36.720.00**
Host interface:	I²C, 3.3V	RS232TTL, 3.3V
Antenna:	integrated	integrated
Downloaded OP System:	iID®3000PRO	iID®3000PRO

*) in development or on inquiry